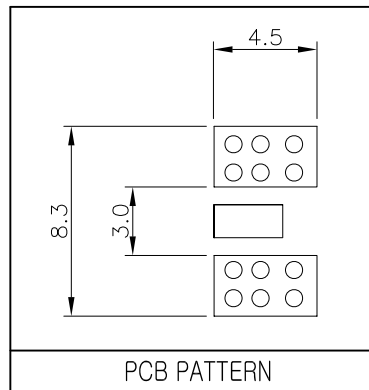
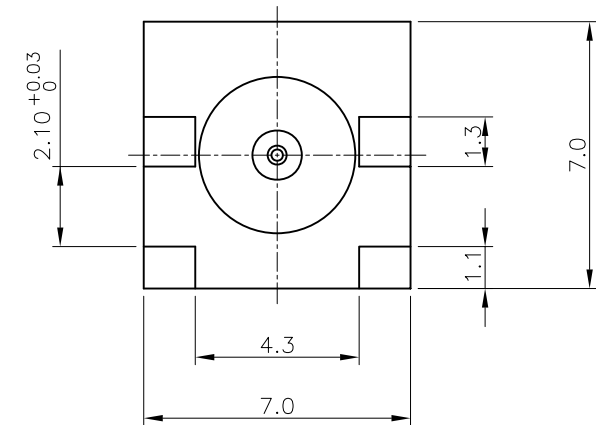
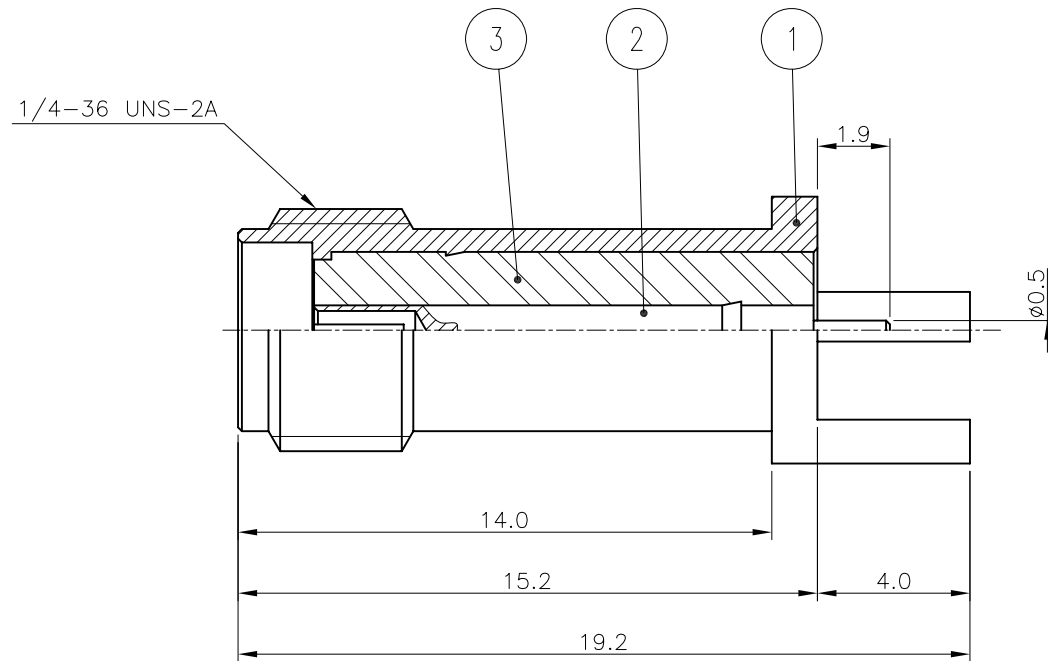


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1 R	Initial Registration	H.J.LEE	I.C.KIM	2016.03.23.



Note

1. PCB thickness (1.9T±10%)

3	INSULATOR	1	TEFLON		DIN02606-N/1
2	CONTACT	1	BeCu C17300 MBsBD	Gold Plate	DCT03666-5/1
1	BODY	1	C3604BD-F	Gold Plate	DBD04139-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 03. 23.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL	-	CHECKED BY		TITLE SMA50 PCB JS-4R (edge)
		DRAWN BY	H.J.LEE	
FINISH	-	SCALE	5/1	DWG NO. CN03581-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	